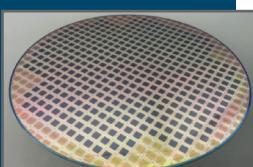
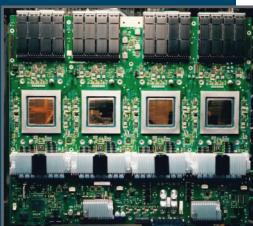
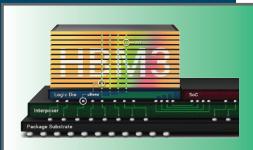


# Advanced Packaging Update: Market and Technology Trends

Vol. 3-1125



This issue of the Advanced Packaging Update provides an analysis of the impact of AI demand on the supply chain including HBM, build-up substrates, and substrate materials. A supply and demand analysis reveals a potential build-up substrate shortage starting in 2027. A progress report on hybrid bonding for a variety of applications is presented and alternatives for 3D stacking are discussed. OSAT financials are provided.

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